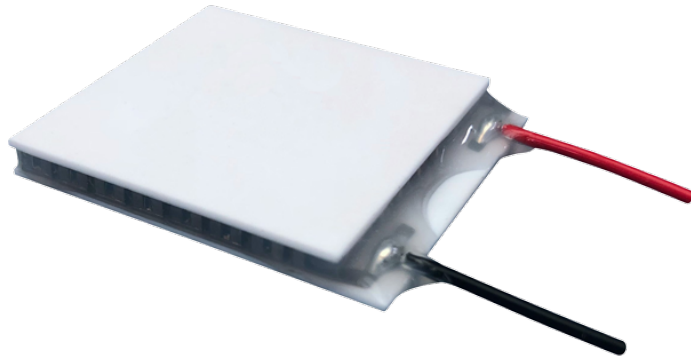


## HiTemp ETX Series Thermoelectric Cooler

The ETX3-12-F2-3030-11-EP-W18 high temperature, high-performance thermoelectric cooler uses Laird Thermal Systems' enhanced thermoelectric module construction preventing performance degrading diffusion, which is common in standard grade thermoelectric coolers operating in high temperature environments exceeding 80 °C. It has a maximum  $Q_c$  of 31.4 Watts when  $\Delta T = 0$  and a maximum  $\Delta T$  of 83.2 °C at  $Q_c = 0$ .

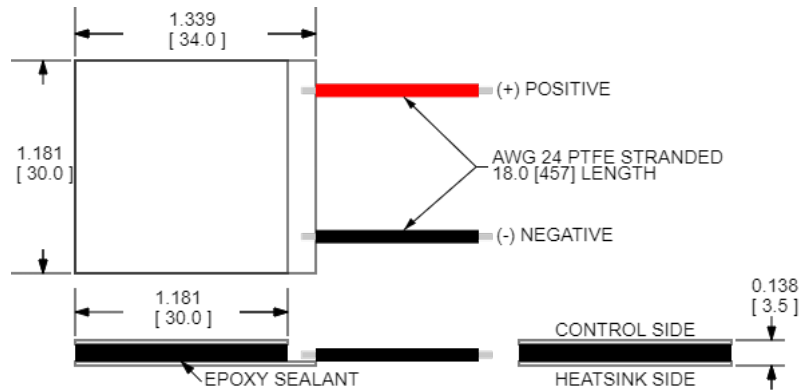


## Features

- High-temperature operation
- Reliable solid-state
- No sound or vibration
- Environmentally-friendly
- RoHS-compliant

## Applications

- [Peltier Cooling for Refrigerated Centrifuges](#)
- [Peltier Cooling for Machine Vision](#)
- [Thermoelectric Cooling for CMOS Sensors](#)
- [Cooling Solutions for Autonomous Systems](#)
- [Peltier Cooling for Digital Light Processors](#)
- [Heating and Cooling for Liquid Chromatography Systems](#)
- [Thermoelectric Cooling for Security Cameras](#)



CERAMIC MATERIAL:  $Al_2O_3$

SOLDER CONSTRUCTION: 232°C, SbSn

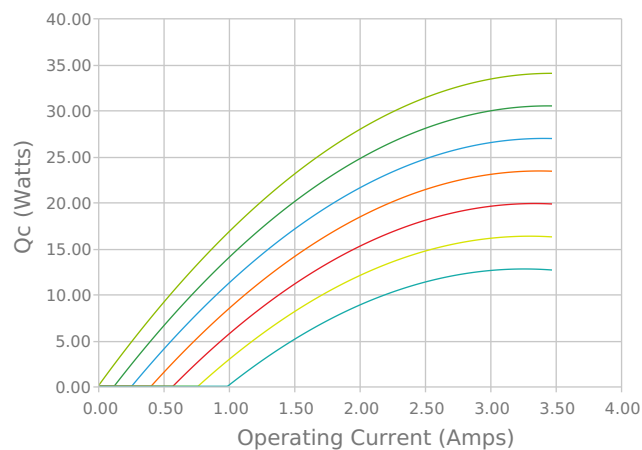
INCHES [MM]

Note: Allow 0.020 in [0.5 mm] around perimeter of the thermoelectric cooler and lead wire attachment to accommodate sealant

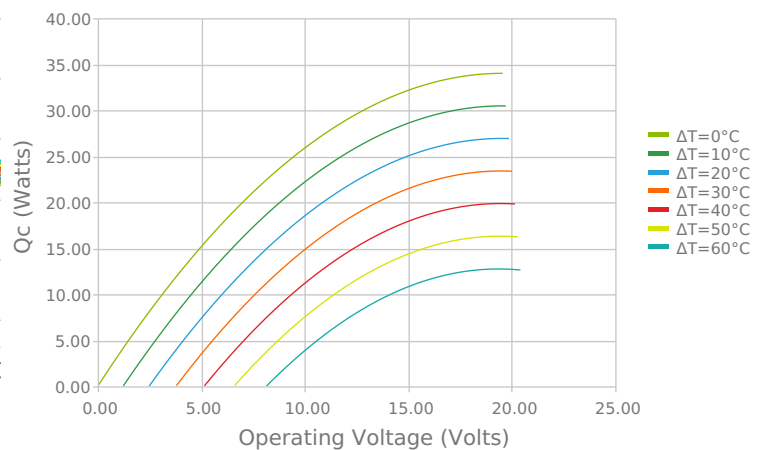
## ELECTRICAL AND THERMAL PERFORMANCE

For maximum performance, be sure to orient the CONTROL side of the TEC against the application to be managed and the HEATSINK side against the heat sink or other heat rejection method. The CONTROL side is always opposite the side with lead attachments. Lead attachment is a passive heat loss and less impactful if located on the side that attaches to the heat exchanger.

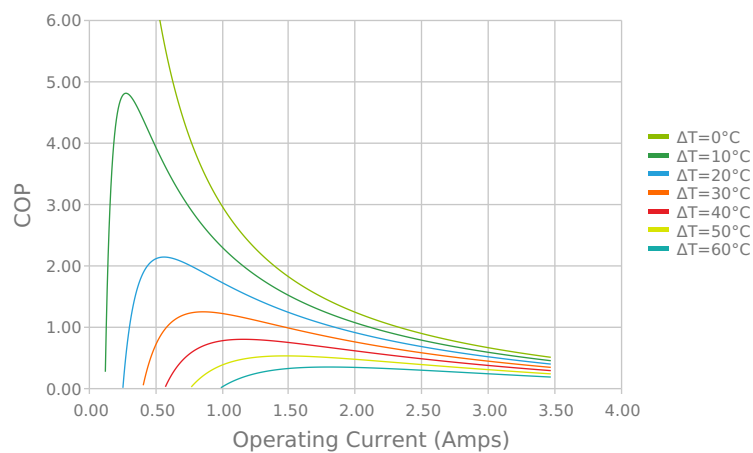
Heat Pumped at Cold Side  
 $T_{hot} = 85\text{ °C}$



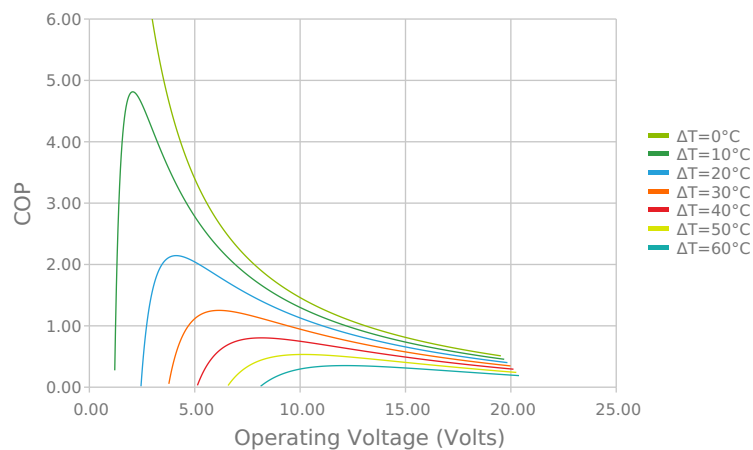
Heat Pumped at Cold Side  
 $T_{hot} = 85\text{ °C}$



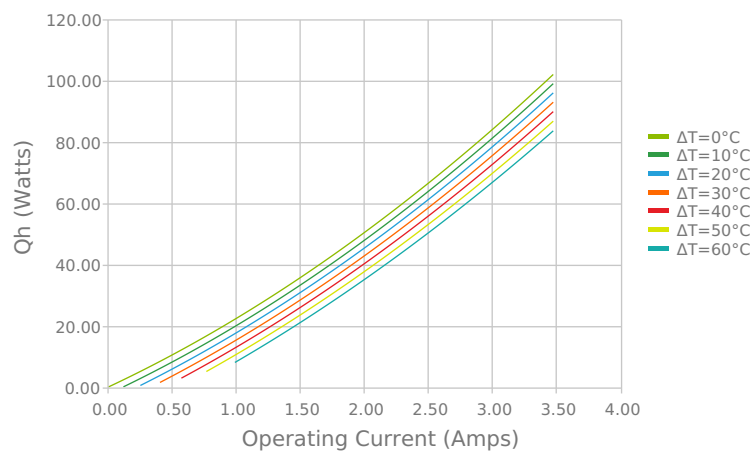
Coefficient of Performance (COP =  $Q_c/P_{in}$ )  
 $T_{hot} = 85\text{ }^{\circ}\text{C}$



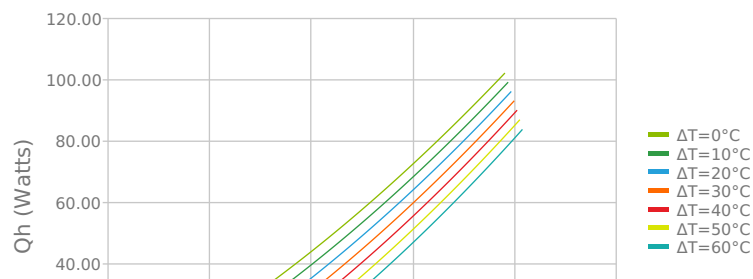
Coefficient of Performance (COP =  $Q_c/P_{in}$ )  
 $T_{hot} = 85\text{ }^{\circ}\text{C}$



Total Heat Dissipated at Hot Side ( $Q_h = Q_c + P_{in}$ )  
 $T_{hot} = 85\text{ }^{\circ}\text{C}$



Total Heat Dissipated at Hot Side ( $Q_h = Q_c + P_{in}$ )  
 $T_{hot} = 85\text{ }^{\circ}\text{C}$



## SPECIFICATIONS\*

### Hot Side Temperature

**Q<sub>cmax</sub> ( $\Delta T = 0$ )**

**$\Delta T_{max}$  ( $Q_c = 0$ )**

**I<sub>max</sub> (I @  $\Delta T_{max}$ )**

**V<sub>max</sub> (V @  $\Delta T_{max}$ )**

**Module Resistance**

**Max Operating Temperature**

**Weight**

**50.0 °C**

**85.0 °C**

**110.0 °C**

31.4 Watts	34.0 Watts	35.1 Watts
83.2 °C	95.3 °C	102.0 °C
3.2 Amps	3.1 Amps	3.0 Amps
16.6 Volts	19.1 Volts	20.8 Volts
4.82 Ohms	5.62 Ohms	6.16 Ohms
150 °C		
9.0 gram(s)		

\* Specifications reflect thermoelectric coefficients updated March 2020

## FINISHING OPTIONS

Suffix	Thickness	Flatness / Parallelism	Hot Face	Cold Face	Lead Length
11	3.510 ± 0.051 mm 0.138 ± 0.0020 in	0.051 mm / 0.051 mm 0.002 in / 0.002 in	Lapped	Lapped	152.4 mm 6.00 in

## SEALING OPTIONS

Suffix	Sealant	Color	Temp Range	Description
EP	Epoxy	Black	-55 to 150 °C	Low density syntactic foam epoxy encapsulant

## NOTES

1. Max operating temperature: 150 °C
2. Do not exceed I<sub>max</sub> or V<sub>max</sub> when operating module
3. Reference assembly guidelines for recommended installation

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Revision: 00 Date: 08-30-2022

Print Date: 07-04-2023